

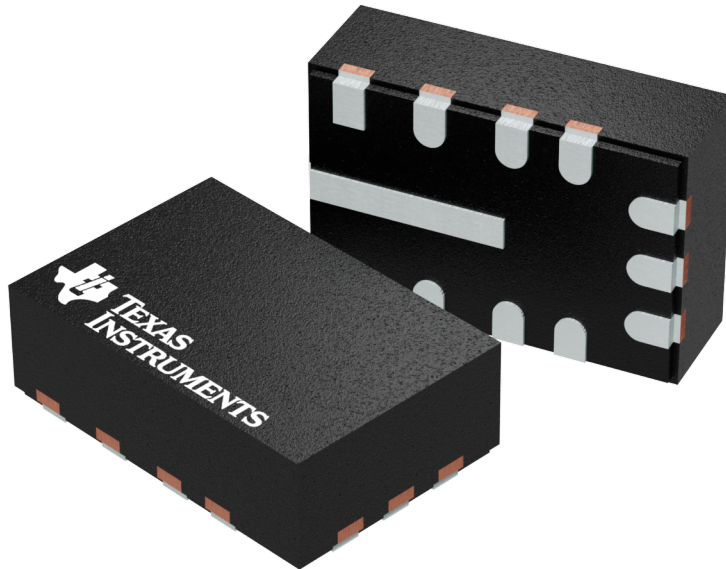
GENERIC PACKAGE VIEW

RNX 12

VQFN-HR - 1 mm max height

2 x 3 mm, 0.5 mm pitch

PLASTIC QUAD FLATPACK-NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4224286/A

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